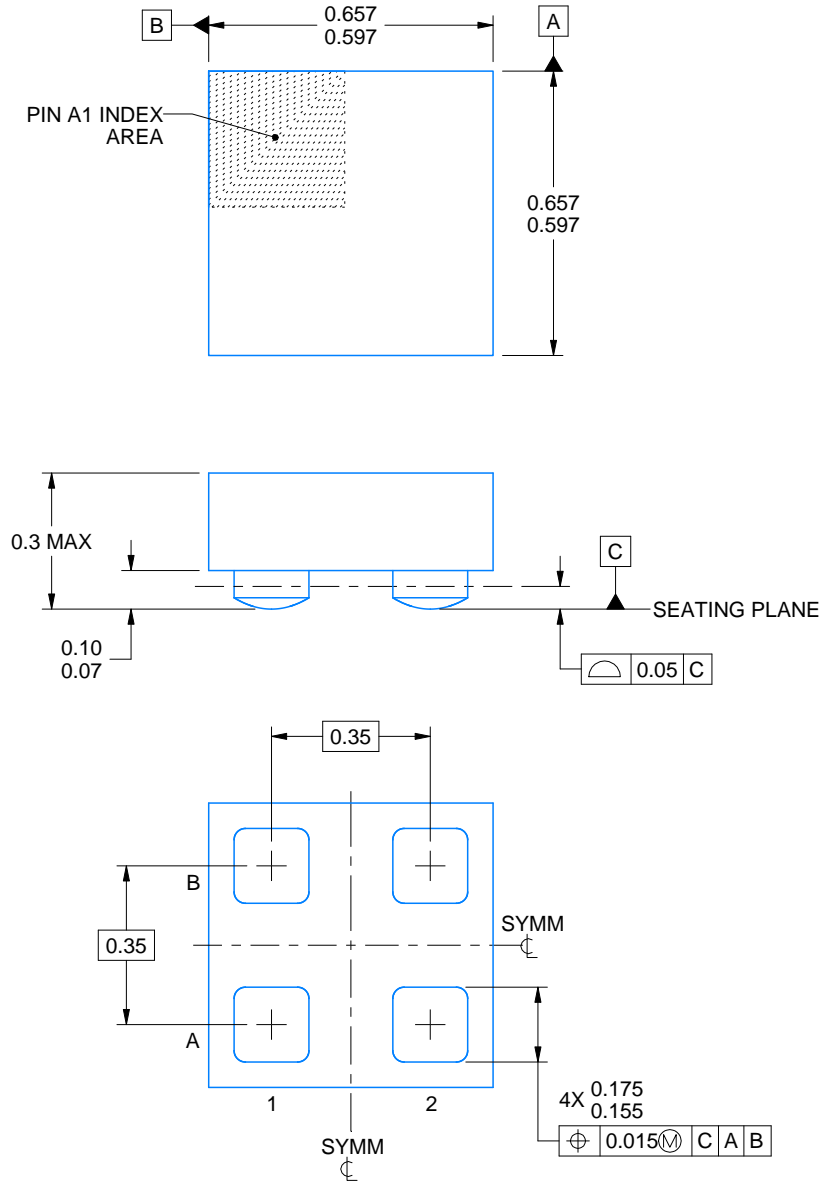


PACKAGE OUTLINE

YWD0004A

PowerWCSP - 0.3 mm max height

POWER CHIP SCALE PACKAGE



4225173/A 07/2019

NOTES:

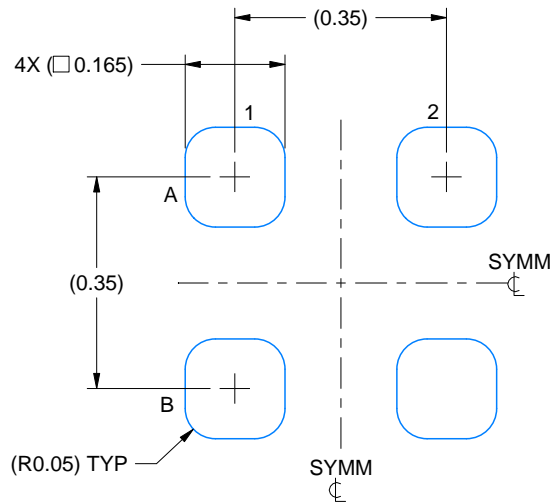
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

EXAMPLE BOARD LAYOUT

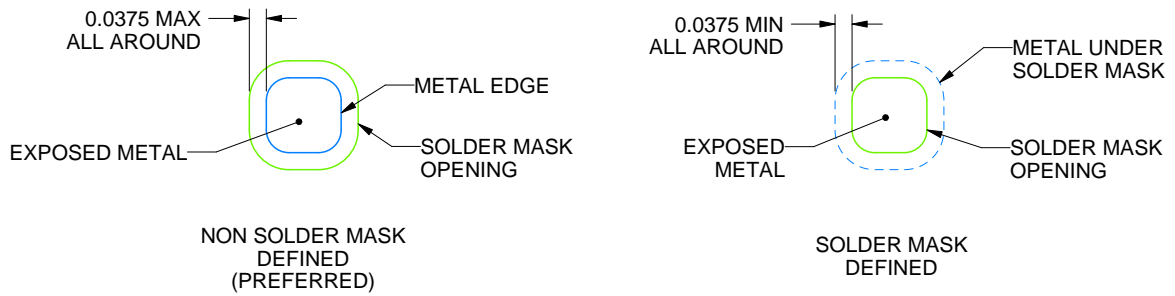
YWD0004A

PowerWCSP - 0.3 mm max height

POWER CHIP SCALE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 80X



SOLDER MASK DETAILS
NOT TO SCALE

4225173/A 07/2019

NOTES: (continued)

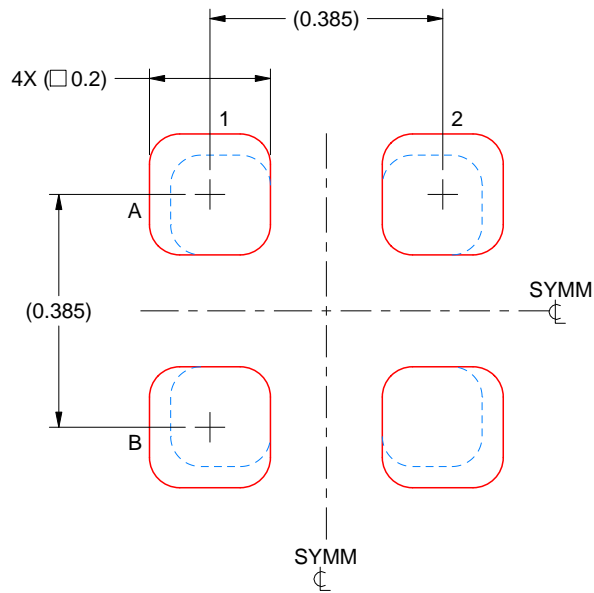
- Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).

EXAMPLE STENCIL DESIGN

YWD0004A

PowerWCSP - 0.3 mm max height

POWER CHIP SCALE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.075 mm THICK STENCIL
SCALE: 80X

4225173/A 07/2019

NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

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